

# MA3SE01

## Silicon epitaxial planar type

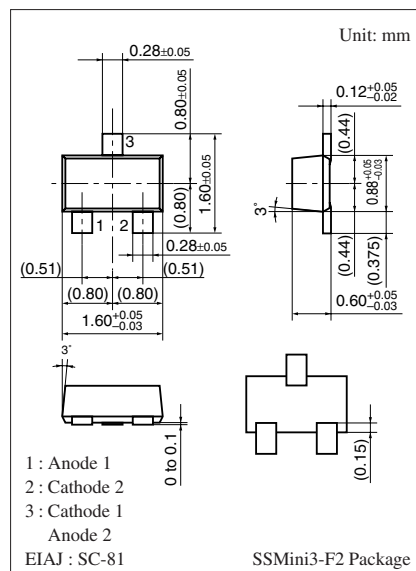
For cellular phone

### ■ Features

- High-frequency wave detection is possible
- Low forward voltage  $V_F$
- Small junction-capacitance

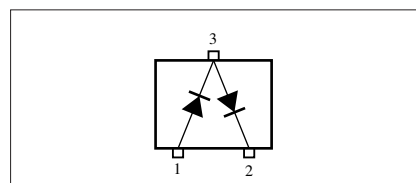
### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter		Symbol	Rating	Unit
Reverse voltage		$V_R$	20	V
Maximum peak reverse voltage		$V_{RM}$	20	V
Forward current	Single	$I_F$	35	mA
	Series		25	
Peak forward current	Single	$I_{FM}$	100	mA
	Series		70	
Junction temperature		$T_j$	125	$^\circ\text{C}$
Storage temperature		$T_{stg}$	-55 to +125	$^\circ\text{C}$



Marking Symbol: M6A

Internal Connection

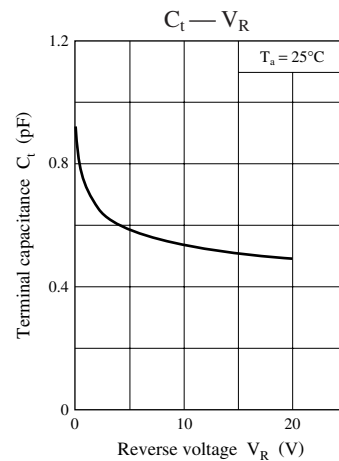
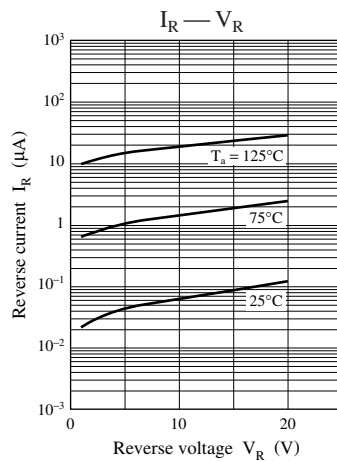
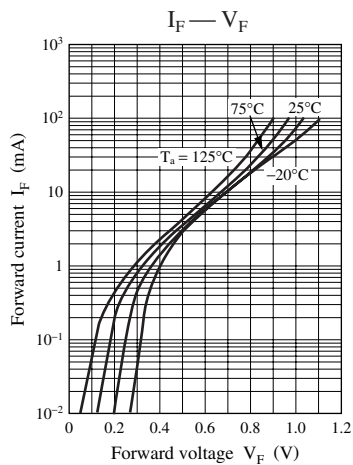


### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_{F1}$	$I_F = 1 \text{ mA}$			0.41	V
	$V_{F2}$	$I_F = 35 \text{ mA}$			1.0	V
Reverse current	$I_R$	$V_R = 15 \text{ V}$			200	nA
Terminal capacitance	$C_t$	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$			1.2	pF
Dynamic resistance	$R_d$	$I_F = 5 \text{ mA}$		40		$\Omega$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 2 GHz



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